L	Hits	Search Text		
Number 1	1		DB	m:
1	11213	die (adj4 pad		Time stamp
			USPAT;	2003/02/22
	i		US-PGPUB;	11:22
			EPO; JPO;	
2	4710791	heat (hers) (sink and	DERWENT;	1
		heat (her5) (sink spreader slug metal	IBM_TDB USPAT;	
			US-PGPUB;	2003/02/22
			EPO; JPO;	11:25
3	5189	wire and (diadja pad) and "4"	DERWENT;	1
	3103	adja pad) and "4"	IBM TDB	1
			USPAT;	2003/02/22
	İ		LGFUD: I	11:25
	i	(semiconductor chip dice ic (integrated adj pad) and adj circuit) die) add (die adj4 pad) and	EPO; JPO;	1
4	6463	(semiconductor chip dice is (integrated adjustment) and (die adjustment) and (die adjustment)	US-PGFOEPO; JPO;	
		adj circuit, dit, iii- j	DERWENT;	
		(wire wiring)	IBM TDB	
		/ / / regrated	USPAT;	2003/02/22
5	6484	(semiconductor chip dic ic (integrated die adj4 pad) and	US-PGPUB;	11:27
Ň			EPO; JPO;	
		(wire wiring wirebond)	DERWENT;	
	,	/	IBM_TDB	2003/02/22
		((semiconductor chip dice ic (integrated	USPAT; US-PGPUB;	11:29
6	2698	((semiconductor chip dice it (integral and adj circuit) die) and (die adj4 pad) and adj circuit) die) and (bga ball	EPO; JPO;	
1			DERWENT;	
	1	(wire wiring wirebold) bump flipchip (flip adj chip))	IBM TDB	100 /33
ļ		ic /integrated	USPAT;	2003/02/22
¦ ·7	2137		US-PGPUB;	11:29
		adj circuit) die) and (dre ab) (wire wiring wirebond)) and (bga ball (wire wiring wirebond)) and	EPO; JPO;	
į		(wire wiring wirebond, and bump flipchip (flip adj chip))) and	DERWENT; IBM TDB	
		substrate	USPAT;	2003/02/22
8	1848	N. and source ton 1 and	US-PGPUB;	11:30
			EPO; JPO;	1
		(integrated adj circuit) die) and (die		1
	į	(linegrated adj circuit) die abond)) and adj4 ad) and (wire wiring wirebond)) and (bga bal bump flipchip (flip adj chip)))	IBM_TDB	1
		and substrate)		2003/02/22
	1390	((cap lid over top) and	USPAT; US-PGPUB;	
9	1390	////semiconductor chip dice 10	EPO; JPO;	
ļ	1	lintagrated abi singuith die and (uic		
				1
	!	I than hall hump flrachin (IIID ad) chip//	,	1
		and substrate)) and (epoxy encapsurate)		2002/02/22
		encapsulation) 5 (((cap lid cover top)) and	USPAT;	2003/02/22
10	35!	1 4 4 4 4 manus applicator chip dice ic	US-PGPUB	; 11:32
	1	1	EPO; JPO	<i>;</i>
1.		I II I /rrive thiring/ Wilebond// arr	d DERWENT;	
	į	1 / Lail humn flinchin (LLID ad) CHIP//) IBM_TDB	1
	ļ	I I I I I I I I I I I I I I I I I I I	1	
1	1	encapsulation)) and (retainer ring guard	<u> </u>	

Search History 2/22/03 11:32:14 AM Page 1